# High Current Ferrite Chip Bead(Lead Free)

HCB3216KF-300T80

ECN HISTORY LIST											
REV	DATE	DESCRIPTION	APPROVED	CHECKED	DRAWN						
1.0	13/06/06	變更可靠度條件	楊祥忠	羅培君	張嘉玲						
2.0	14/01/24	變更電鍍錫層厚度 3.0um min.=>3.5um min.	楊祥忠	羅培君	張嘉玲						
3.0	14/08/01	變更 Reflow 圖示	楊祥忠	羅培君	張嘉玲						
3.1	14/08/01	修正包裝帶尺寸	楊祥忠	羅培君	張嘉玲						
4.0	16/01/26	增訂可靠度 Thermal shock: (Bead) Step3:125±2℃ 30±5min	楊祥忠	詹偉特	張嘉玲						
5.0	17/02/16	修訂 Recommended PC Board Pattern	楊祥忠	詹偉特	張嘉玲						
備											
νΗ											
註											

**TAI-TECH** KBM01-180900278 P2.

# High Current Ferrite Chip Bead(Lead Free)

HCB3216KF-300T80

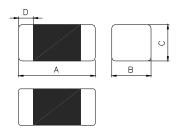
Certificate

Green Partner

## 1.Features

- 1. Monolithic inorganic material construction.
- 2. Closed magnetic circuit avoids crosstalk.
- 3. Suitable for reflow soldering.
- 4. Shapes and dimensions follow E.I.A. spec.
- 5. Available in various sizes.
- 6. Excellent solder ability and heat resistance.
- 7. High reliability.
- 8.100% Lead(Pb) & Halogen-Free and RoHS compliant.
- 9. Low DC resistance structure of electrode to prevent wasteful electric power consumption.

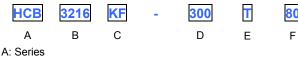
## 2. Dimensions



Chip Size					
Α	3.20±0.20				
В	1.60±0.20				
С	1.10±0.20				
D	0.50±0.30				

Units: mm

## 3.Part Numbering



B: Dimension

C: Material

D: Impedance

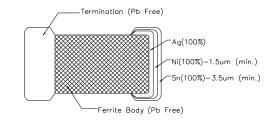
E: Packaging

Lead Free Material 300=30  $\Omega$ 

LxW

T=Taping and Reel, B=Bulk(Bags)

F: Rated Current

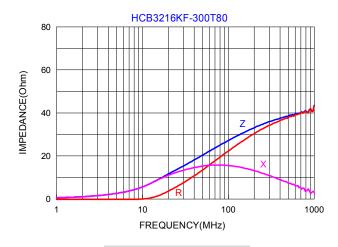


## 4. Specification

Tai-Tech Part Number	Impedance ( $\Omega$ )	Test Frequency (Hz)	DC Resistance $(\Omega)$ max.	Rated Current (mA) max.
HCB3216KF-300T80	30±25%	60mV/100M	0.01	8000

- Rated current: based on temperature rise test
- In compliance with EIA 595

### Impedance-Frequency Characteristics



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## 5. Reliability and Test Condition

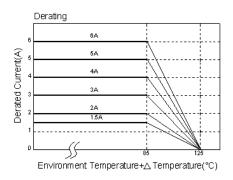
Item			Performance				Te	st Cond	dition	
Series No.	FCB	FCM	<mark>HCB</mark>	GHB	FCA					
Operating Temperature		(Includir	-55∼+125℃ ng self-temperati	ure rise)						
Transportation Storage Temperature			-55~+125℃ (on board)			For long			ons, please	see the
Impedance (Z)	Refer to stan	dard electrical cha	aractoristics list			Agilent4: Agilent E Agilent4: Agilent11	E4991 287			
DC Resistance Rated Current	- Neier to stand	aara creemear one	aracteristics list			Agilent 4	338 er Supp ted Curr		ements, the	ere will be
Temperature Rise Test		1A ΔT 20℃Max : 1A ΔT 40℃Max				1. Applie 2. Tempe	d the all	lowed DC measured	current. by digital su	urface
Life test		no damage. vithin±15%of initia vithin±10%of initia				times.( II Reflow F Tempera Applied Duration Measure for 24±2	PC/JED Profiles) ature: 12 current: : 1000± ed at ro hrs.	EC J-STD 5±2°C rated curn 12hrs. om tempe	ugh IR refl I-020D Clas ent. erature afte	esification
Load Humidity	Q : Shall not	exceed the specii	fication value.	exceed the spe	cification value	Reflow F Humidity Tempera Duration current.	Profiles) v: 85±2% uture: 85 v: 1000 ed at ro	bR.H. ±2℃. hrs Min.	with 100 erature afte	% rated
Thermal shock	Inductance: v Q : Shall not	no damage. vithin±15%of initia vithin±10%of initia exceed the speci ±15% of initial va	ll value. fication value.	exceed the spe	cification value	Precond times.( II Reflow F Conditio Step1: -5 Step2: 2 Step3: + Number	itioning: PC/JED Profiles) In for 1 co 55±2°C 5±2°C 125±2°C of cycle ed at ro	eycle 30±5 ≤ 0.5n 30±5m 5: 500	nin	ssification
Vibration	Inductance : Q : Shall not	No damage. within±15% of iniwithin±10% of initexceed the speci±15% of initial va	ial value fication value.	exceed the spe	cification value	times.( II Reflow F Oscillation minutes Equipment Total Am	PC/JED Profiles) on Freq ent : Vi plitude: Time : 1.	EC J-STD uency: 10 bration chi 1.52mm±1 2 hours(20		ssification
Bending	Impedance : Inductance : Q : Shall not	No damage. within±10% of ini within±10% of init exceed the speci ±15% of initial va	ial value fication value.	exceed the spe	cification value	following >=0805in <0805in Bending >=0805in <0805in	dimens nch(201 ch(2012 depth: nch(201 ch(2012	ions: 2mm):40x	m	
Shock	Impedance : Inductance :	No damage. within±10% of initivitinin±10% of initivities.	tial value			Test co	Peak Value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (Vi)ft/sec
		±15% of initial va		exceed the spe	cification value	SMD	50 50	11	Half-sine Half-sine	11.3
Solderability	More than 95°	% of the terminal o	electrode should	be covered with	n solder.	Solder to	Sn96.5% emperations lead free omplete	5-Ag3%-C ure: 245±5 e: Rosin. 9 ly cover th	5℃	on.

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Item	Performance		Те	st Con	dition
			Number of heat	cycles: 1	
Resistance to Soldering	Appearance : No damage. Impedance : within±15% of initial value	Temperature (°C)	Time (s)	Temperature ramp/immersion and emersion rate	
Heat	Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not	260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s	
			Depth: complete	ely cover t	he termination
Terminal strength	Appearance: No damage. Impedance: within±15% of initial value Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within±15% of initial value and shall not exceed the specification value	radius 0,5 mm  DUT  wide  wide  wide  whickness  shear force	times.( IPC/JED) Reflow Profiles) Component moi >0805inch(2012 <=0805inch(2010) to the side of a shall be applied	unted on a 2mm):1kg 12mm):0.5 device bei d for 60 + oplied grad	ing tested. This force 1 seconds. Also the dually as not to shock

### \*\*Derating Curve

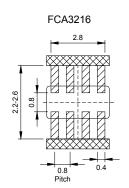
For the ferrite chip bead which withstanding current over 1.5A, as the operating temperature over  $85^{\circ}\mathbb{C}$ , the derating current information is necessary to consider with. For the detail derating of current, please refer to the Derated Current vs. Operating Temperature curve.



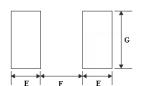
## 6. Soldering and Mounting

#### 6-1. Recommended PC Board Pattern

	Chip Size							s For ering	
Series	Type	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)	F(mm)	G(mm)	
	0603	0.6±0.03	0.30±0.03	0.30±0.03	0.15±0.05	0.35	0.30	0.40	
FCB	1005	1.0±0.10	0.50±0.10	0.50±0.10	0.25±0.10	0.50	0.40	0.60	
FCM	1608	1.6±0.15	0.80±0.15	0.80±0.15	0.30±0.20	0.80	0.85	0.95	
HCB	0040	2.0±0.20	1.25±0.20	0.85±0.20	0.50±0.30	4.05	4.05	4.00	4.45
GHB	2012	2.0±0.20	1.25±0.20	1.25±0.20	0.50±0.30	1.05	1.00	1.45	
FCI	<mark>3216</mark>	3.2±0.20	1.60±0.20	1.10±0.20	0.50±0.30	<mark>1.05</mark>	<mark>2.20</mark>	<mark>1.80</mark>	
FHI	3225	3.2±0.20	2.50±0.20	1.30±0.20	0.50±0.30	1.05	2.20	2.70	
FCH	4516	4.5±0.20	1.60±0.20	1.60±0.20	0.50±0.30	1.05	3.30	1.80	
HCI	4532	4.5±0.20	3.20±0.20	1.50±0.20	0.50±0.30	1.05	3.30	3.40	



∠∠∠ Land Solder Resist



PC board should be designed so that products can prevent damage from mechanical stress when warping the board.

## 6-2. Soldering

Mildly activated rosin fluxes are preferred. The terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

Note.

If wave soldering is used ,there will be some risk.

Re-flow soldering temperatures below 240 degrees, there will be non-wetting risk

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### 6-2.1 Lead Free Solder re-flow:

Recommended temperature profiles for lead free re-flow soldering in Figure 1. (Refered to J-STD-020C)

#### 6-2.2 Soldering Iron:

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. If a soldering iron must be employed the following precautions are recommended. for Iron Soldering in Figure 2.

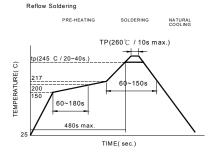
• Preheat circuit and products to 150℃

• 350 $^{\circ}$ C tip temperature (max)

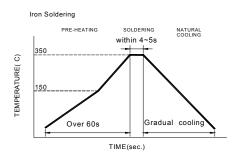
Never contact the ceramic with the iron tip

• 1.0mm tip diameter (max)

- Use a 20 watt soldering iron with tip diameter of 1.0mm
- Limit soldering time to 4~5sec.



Reflow times: 3 times max Fig.1

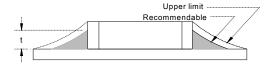


Iron Soldering times: 1 times max

#### 6-2.3 Solder Volume:

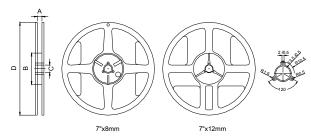
Accordingly increasing the solder volume, the mechanical stress to product is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance. Solder shall be used not to be exceed as shown in right side:

Minimum fillet height = soldering thickness + 25% product height



## 7. Packaging Information

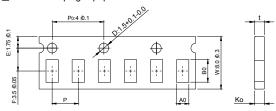
### 7-1. Reel Dimension



Туре	A(mm)	B(mm)	C(mm)	D(mm)
<mark>7"x8mm</mark>	9.0±0.5	60±2	13.5±0.5	<mark>178±2</mark>
7"x12mm	13.5±0.5	60±2	13.5±0.5	178±2

#### 7-2.1 Tape Dimension / 8mm

## ■Material of taping is paper



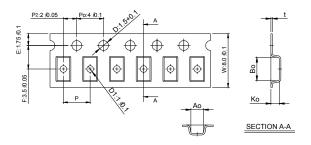
E:1.75.90.1	P22.0.1 P04.0.1 0.1660.1.056	<b>+ - - -</b>	- t
F:3.5.0.1	P	40 80 80 80 80 80	Ко

Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)
060303	0.70±0.06	0.40±0.06	0.45max	2.0±0.05	0.45max
100505	1.12±0.03	0.62±0.03	0.60±0.03	2.0±0.05	0.60±0.03

Size	Bo(mm) Ao(mm)		Ko(mm)	P(mm)	t(mm)
160808	1.80±0.05	0.96+0.05/-0.03	0.95±0.05	4.0±0.10	0.95±0.05
201209	2.10±0.05	1.30±0.05	0.95±0.05	4.0±0.10	0.95±0.05

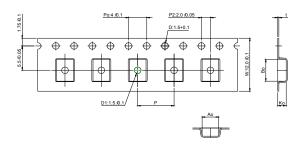
**TAI-TECH** KBM01-180900278 P6.

■Material of taping is plastic



Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)	D1(mm)
201212	2.10±0.10	1.28±0.10	1.28±0.10	4.0±0.10	0.22±0.05	1.0±0.10
<mark>321611</mark>	3.35±0.10	1.75±0.10	1.25±0.10	4.0±0.10	0.23±0.05	1.0±0.10
322513	3.42±0.10	2.77±0.10	1.55±0.10	4.0±0.10	0.22±0.05	1.0±0.10
321609	3.40±0.10	1.77±0.10	1.04±0.10	4.0±0.10	0.22±0.05	1.0±0.10

#### 7-2.2 Tape Dimension / 12mm

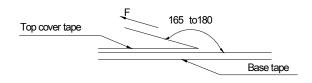


Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)	D1(mm)
451616	4.70±0.10	1.75±0.10	1.75±0.10	4.0±0.10	0.24±0.05	1.5±0.10
453215	4.70±0.10	3.45±0.10	1.60±0.10	8.0±0.10	0.24±0.05	1.5±0.10

#### 7-3. Packaging Quantity

Chip Size	453215	451616	322513	<mark>321611</mark>	321609	201212	201209	160808	100505	060303
Chip / Reel	1000	2000	2500	<mark>3000</mark>	3000	2000	4000	4000	10000	15000
Inner box	4000	8000	12500	<mark>15000</mark>	15000	10000	20000	20000	50000	75000
Middle box	20000	40000	62500	<mark>75000</mark>	75000	50000	100000	100000	250000	375000
Carton	40000	80000	125000	<mark>150000</mark>	150000	100000	200000	200000	500000	750000

### 7-4. Tearing Off Force



The force for tearing off cover tape is 15 to 60 grams in the arrow direction under the following conditions.

Room Temp.	Room Humidity	Room atm	Tearing Speed	
(℃)	(%)	(hPa)	mm/min	
5~35	45~85	860~1060	300	

## **Application Notice**

Storage Conditions(component level)

To maintain the solder ability of terminal electrodes:

- 1. TAI-TECH products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
- 2. Temperature and humidity conditions: Less than 40°C and 60% RH.
- 3. Recommended products should be used within 12 months from the time of delivery.
- 4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
- 1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- 2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
- 3. Bulk handling should ensure that abrasion and mechanical shock are minimized.



**Test Report** 

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日期(Date): 2017/12/12

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(慶邦電子元器件(泗洪) 有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

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以下測試樣品係由申請廠商所提供及確認 (The following sample(s) was/were submitted and identified by/on behalf of the applicant as):

樣品名稱(Sample Description)

: FERRITE CHIP BEAD INDUCTOR ARRAY MCF MCM YMV SERIES

樣品型號(Stvle/Item No.)

FERRITE CHIP BEAD INDUCTOR ARRAY MCF MCM YMV SERIES

收件日期(Sample Receiving Date)

2017/12/05

測試期間(Testing Period)

2017/12/05 TO 2017/12/12

測試結果(Test Results) :

請參閱下一頁 (Please refer to following pages).

Signed for and on being SGS TAIWAN LTD. Chemical Laboratory - Taipei

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**Test Report** 

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### 測試結果(Test Results)

測試部位(PART NAME)No.1

: 整體混測 (MIXED ALL PARTS)

測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	方法侦测 極限値 (MDL)	結果 (Result) No.1
錦 / Cadmium (Cd)	mg/kg	参考IEC 62321-5 (2013),以感應耦合 電漿原子發射光譜儀檢測. / With reference to IEC 62321-5 (2013) and performed by ICP-AES.	2	n. d.
鉛 / Lead (Pb)	mg/kg	参考IEC 62321-5 (2013),以感應耦合電漿原子發射光譜儀檢測. / With reference to IEC 62321-5 (2013) and performed by ICP-AES.	2	n. d.
汞 / Mercury (Hg)	mg/kg	参考IEC 62321-4 (2013),以感應耦合 電漿原子發射光譜儀檢測. / With reference to IEC 62321-4 (2013) and performed by ICP-AES.	2	n. d.
六價絡 / Hexavalent Chromium Cr(VI) (◆)	mg/kg	参考IEC 62321-7-2 (2017),以UV-VIS 檢測;参考IEC 62321-5 (2013),以 ICP-AES檢測. / With reference to IEC 62321-7-2 (2017) and performed by UV-VIS.; With reference to IEC 62321-5 (2013) and performed by ICP-AES.	8	n, d,
绨 / Antimony (Sb)	mg/kg	参考US EPA 3052 (1996),以感應耦合 電漿原子發射光譜儀檢測. / With reference to US EPA 3052 (1996). Analysis was performed by ICP-AES.	2	n. d.

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**Test Report** 

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測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	方法偵測 極限値 (MDL)	結果 (Result)
种 / Arsenic (As)	mg/kg	参考US EPA 3052 (1996),以感應耦合 電漿原子發射光譜儀檢測. / With reference to US EPA 3052 (1996). Analysis was performed by ICP-AES.	2	No. 1 n. d.
鈹 / Beryllium (Be)	mg/kg	参考US EPA 3052 (1996),以感應耦合 電漿原子發射光譜儀檢測. / With reference to US EPA 3052 (1996). Analysis was performed by ICP-AES.	2	n. d.
全氟辛烷磺酸 / Perfluorooctane sulfonates (PFOS-Acid, Metal Salt, Amide)	mg/kg	參考US EPA 3550C (2007),以液相層 析/質譜儀檢測. / With reference to US EPA 3550C (2007). Analysis was performed by LC/MS.	10	n, d,
全氟辛酸 / PFOA (CAS No.: 335-67-1)	mg/kg	參考US EPA 3550C (2007),以液相層 析/質譜儀檢測. / With reference to US EPA 3550C (2007). Analysis was performed by LC/MS.	10	n. d.
聚氯乙烯 / PVC	**	以紅外光譜分析及焰色法檢測. / Analysis was performed by FTIR and FLAME Test.	-	Negative
鄰苯二甲酸丁苯甲酯 / BBP (Butyl Benzyl phthalate) (CAS No.: 85-68-7)	mg/kg		50	n, d.
鄰苯二甲酸二丁酯 / DBP (Dibuty1 mg/kg phthalate) (CAS No.: 84-74-2)		→ 参考IEC 62321-8 (2017),以氣相層析 儀/質譜儀檢測. / With reference to	50	n. d.
鄰苯二甲酸二 (2-乙基己基)酯 / DEHP (Di- (2-ethylhexyl) phthalate) (CAS No.: 117-81-7)	mg/kg	IEC 62321-8 (2017). Analysis was performed by GC/MS.	50	n. d.

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測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	方法偵測 極限值 (MDL)	結果 (Result) No.1
鄰苯二甲酸二異丁酯 / DIBP (Di- isobutyl phthalate) (CAS No.: 84-69- 5)	mg/kg		50	n. d.
鄭苯二甲酸二異癸酯 / DIDP (Di- isodecyl phthalate) (CAS No.: 26761- 40-0; 68515-49-1)	mg/kg		50	n. d.
鄰苯二甲酸二異壬酯 / DINP (Di- isononyl phthalate) (CAS No.; 28553- 12-0; 68515-48-0)	mg/kg	參考IEC 62321-8 (2017),以氣相層析 儀/質譜儀檢測. / With reference to IEC 62321-8 (2017). Analysis was	50	n. d.
鄰苯二甲酸二正辛酯 / DNOP (Di-n-octyl phthalate) (CAS No.: 117-84-0)	mg/kg	performed by GC/MS.	50	n. d.
鄭苯二甲酸二正己酯 / DNHP (Di-n-hexyl phthalate) (CAS No.: 84-75-3)	mg/kg		50	n. d.
鄰苯二甲酸二戊酯 / Di-n-pentyl phthalate (CAS No.: 131-18-0)	mg/kg		50	n. d.
六溴環十二烷及所有主要被辨別出的異構物 / Hexabromocyclododecane (HBCDD) and all major diastereoisomers identified ( $\alpha$ - HBCDD, $\beta$ - HBCDD, $\gamma$ - HBCDD) (CAS No.: 25637-99-4 and 3194-55-6 (134237-51-7, 134237-50-6, 134237-52-8))	ug/kg	多考IEC 62321 (2008),以氣相層析/ 質譜儀檢測. / With reference to IEC 62321 (2008). Analysis was performed by GC/MS.	5	n. d.

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測試項目 (Test Items)	單位 (Unit)	测試方法 (Method)	方法偵測 極限値 (MDL)	結果 (Result) No.1
多溴聯苯總和 / Sum of PBBs	mg/kg			n. d.
一溴聯苯 / Monobromobiphenyl	mg/kg		5	n. d.
二溴聯苯 / Dibromobiphenyl	mg/kg		5	n, d.
三溴聯苯 / Tribromobiphenyl	mg/kg		5	n, d,
四溴聯苯 / Tetrabromobiphenyl	mg/kg		5	n, d,
五溴聯苯 / Pentabromobiphenyl	mg/kg		5	n. d.
六溴聯苯 / Hexabromobiphenyl	mg/kg		5	n. d.
七溴聯苯 / Heptabromobiphenyl	mg/kg		5	n. d.
へ溴聯苯 / Octabromobiphenyl	mg/kg		5	n. d.
九溴聯苯 / Nonabromobiphenyl	mg/kg	参考IEC 62321-6 (2015),以氣相層析	5	n. d.
十溴聯苯 / Decabromobiphenyl	mg/kg	/質譜儀檢測. / With reference to	5	n. d.
多溴聯苯醚總和 / Sum of PBDEs	mg/kg	IEC 62321-6 (2015) and performed		n. d.
一溴聯苯醚 / Monobromodiphenyl ether	mg/kg	by GC/MS.	5	n. d.
二溴聯苯醚 / Dibromodiphenyl ether	mg/kg		5	n. d.
三溴聯苯醚 / Tribromodiphenyl ether	mg/kg		5	n. d.
四溴聯苯醚 / Tetrabromodiphenyl ether	mg/kg		5	n. d.
五溴聯苯醚 / Pentabromodiphenyl ether	mg/kg		5	n. d.
六溴聯苯醚 / Hexabromodiphenyl ether	mg/kg		5	n. d.
七溴聯苯醚 / Heptabromodiphenyl ether	mg/kg		5	n. d.
八溴聯苯醚 / Octabromodiphenyl ether	mg/kg		5	n. d.
九溴聯苯醚 / Nonabromodiphenyl ether	mg/kg		5	n. d.
十溴聯苯醚 / Decabromodiphenyl ether	mg/kg		5	n. d.

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测試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	方法偵測 極限値 (MDL)	結果 (Result) No.1
鹵素 / Halogen				
鹵素(氟)/ Halogen-Fluorine(F) (CAS No.: 14762-94-8)	mg/kg		50	n. d.
鹵素(氣)/ Halogen-Chlorine (C1) (CAS No.: 22537-15-1)	mg/kg	参考BS EN 14582 (2016),以離子層析 儀分析,/ With reference to BS EN	50	n. d.
鹵素(溴)/ Halogen-Bromine (Br) (CAS No.: 10097-32-2)	mg/kg	14582 (2016). Analysis was performed by IC.	50	n. d.
鹵素(碘)/ Halogen-Iodine(I)(CAS No.: 14362-44-8)	mg/kg		50	n. d.

## 備註(Note):

- 1. mg/kg = ppm ; 0.1wt% = 1000ppm
- 2. n.d. = Not Detected (未檢出)
- 3. MDL = Method Detection Limit (方法偵測極限值)
- 4. "-" = Not Regulated (無規格值)
- 5. \*\*= Qualitative analysis (No Unit) 定性分析(無單位)
- 6. Negative = Undetectable 陰性(未偵測到); Positive = Detectable 陽性(已偵測到)
- 7. (•):

若鉻含量小於六價鉻之方法偵測極限值,則六價鉻為n,d,,不須再測試六價鉻。

The result of Cr(VI) is "n.d." as the result of Chromium (Cr) is less than the MDL of Cr(VI), and confirmation test of Cr(VI) is not required.

若鉻含量未小於六價鉻之方法偵測極限值,需進行六價鉻測試。

If the Chromium (Cr) content is not less than the MDL of Cr(VI), confirmation test of Cr(VI) is required.

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8. 樣品的測試是基於申請人要求混合測試,報告中的混合測試結果不代表其中個別單一材質的含量. (The samples was/were analyzed on behalf of the applicant as mixing sample in one testing. The above results was/were only given as the informality value.)

## PFOS參考資訊(Reference Information): 持久性有機污染物 POPs - (EU) 757/2010

PFOS濃度在物質或製備中不得超過0.001%(10ppm),在半成品、成品或零部件中不得超過0.1%(1000ppm),在紡織品或塗層材料中不得超過 $1\mu g/m^2$ 。

(Outlawing PFOS as substances or preparations in concentrations above 0.001% (10ppm), in semi-finished products or articles or parts at a level above 0.1%(1000ppm), in textiles or other coated materials above  $1\mu g/m^2$ .)

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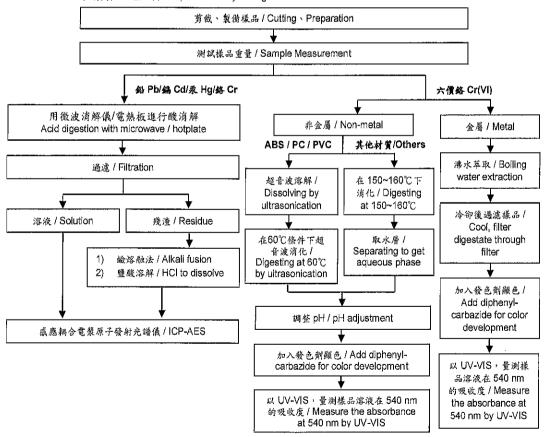
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### 重金屬流程圖 / Analytical flow chart of Heavy Metal

根據以下的流程圖之條件,樣品已完全溶解。(六價鉻測試方法除外)

These samples were dissolved totally by pre-conditioning method according to below flow chart. (Cr6+ test method excluded)

- 測試人員:王志瑋 / Technician : JR Wang
- 测試負責人: 張啟興 / Supervisor: Troy Chang



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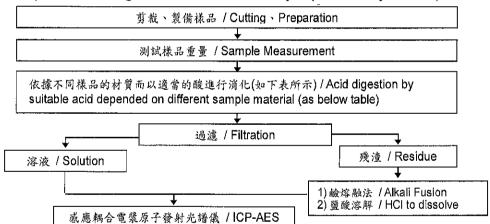
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> 根據以下的流程圖之條件,樣品已完全溶解。 / These samples were dissolved totally by pre-conditioning method according to below flow chart.

- 測試人員:王志瑋 / Technician: JR Wang
- 測試負責人:張啟興 / Supervisor: Trov Chang

## 元素以 ICP-AES 分析的消化流程圖 (Flow Chart of digestion for the elements analysis performed by ICP-AES)



鋼,銅,鉛,焊錫 / Steel, copper, aluminum, solder	王水,硝酸,鹽酸,氫氟酸,雙氧水 /
	Aqua regia, HNO <sub>3</sub> , HCl, HF, H <sub>2</sub> O <sub>2</sub>
玻璃 / Glass	硝酸,氫氟酸 / HNO3/HF
金,鉑,鲍,陶瓷 / Gold, platinum, palladium, ceramic	王水 / Aqua regia
銀 / Silver	硝酸 / HNO3
塑膠 / Plastic	硫酸,雙氧水,硝酸,鹽酸 / H2SO4, H2O2, HNO3, HCI
其他 / Others	加入適當的試劑至完全溶解 / Added appropriate
	reagent to total digestion

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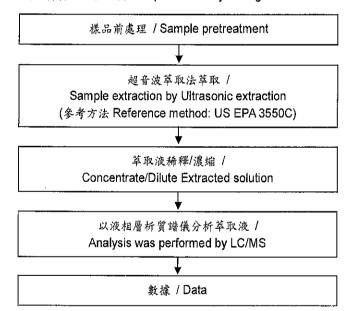
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## 全氯辛酸/全氟辛烷磺酸分析流程圖 / Analytical flow chart - PFOA/PFOS

■ 測試人員:涂雅苓 / Technician: Yaling Tu

測試負責人:張啟與 / Supervisor: Troy Chang



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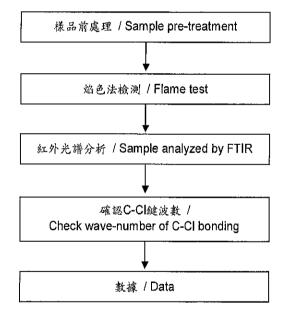
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## 聚氯乙烯物質判定分析流程圖 / Analysis flow chart - PVC

測試人員:涂雅苓 / Technician: Yaling Tu

測試負責人:張啟興 / Supervisor: Troy Chang



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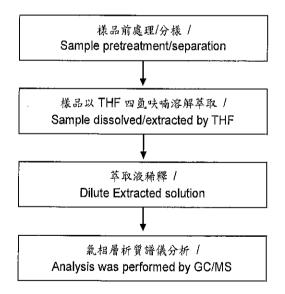
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### <u>可塑劑分析流程圖 / Analytical flow chart - Phthalate</u>

測試人員:徐毓明 / Technician: Andy Hsu

測試負責人:張啟興 / Supervisor: Troy Chang

【测試方法/Test method: IEC 62321-8】



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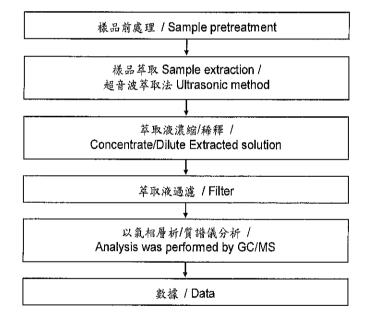
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## 六溴環十二烷分析流程圖 / Analytical flow chart - HBCDD

- 測試人員;涂雅苓 / Technician: Yaling Tu
- 測試負責人:張啟興 / Supervisor: Troy Chang



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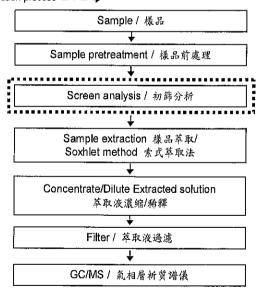
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## 多溴聯苯/多溴聯苯醚分析流程圖 / Analytical flow chart - PBB/PBDE

測試人員:涂雅苓 / Technician: Yaling Tu

測試負責人:張啟興 / Supervisor: Troy Chang

初次测試程序 / First testing process \_ 確認程序 / Confirmation process \_ - - - →



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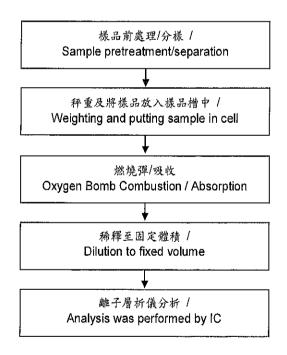
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### <u>由素分析流程圖 / Analytical flow chart - Halogen</u>

- 測試人員:陳恩臻 / Technician: Rita Chen
- 測試負責人:張啟興 / Supervisor: Troy Chang



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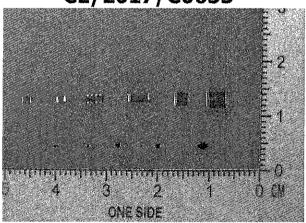
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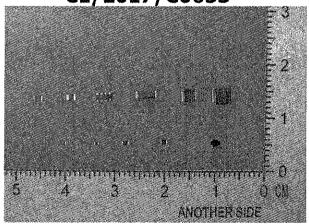
\* 照片中如有箭頭標示,則表示為實際檢測之樣品/部位. \*

(The tested sample / part is marked by an arrow if it's shown on the photo.)

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